



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

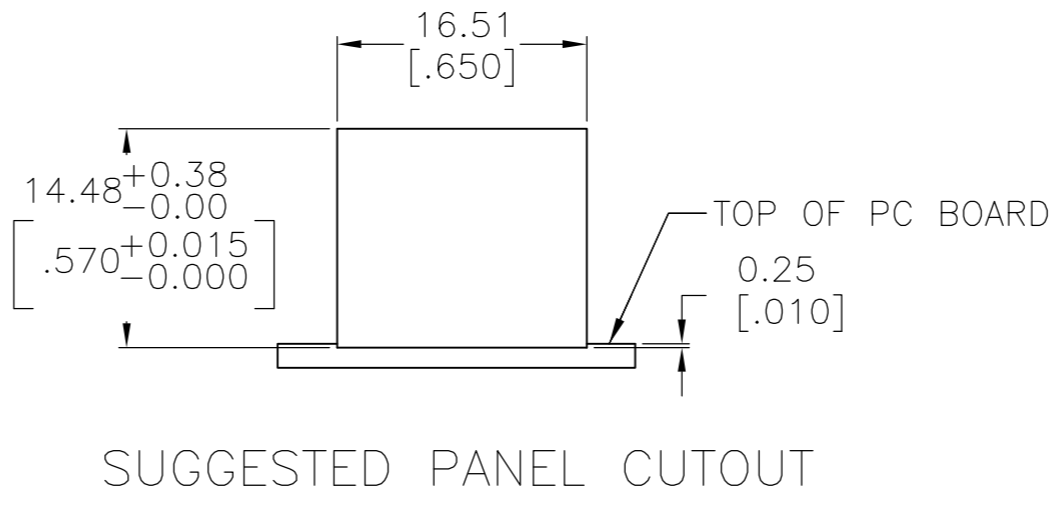
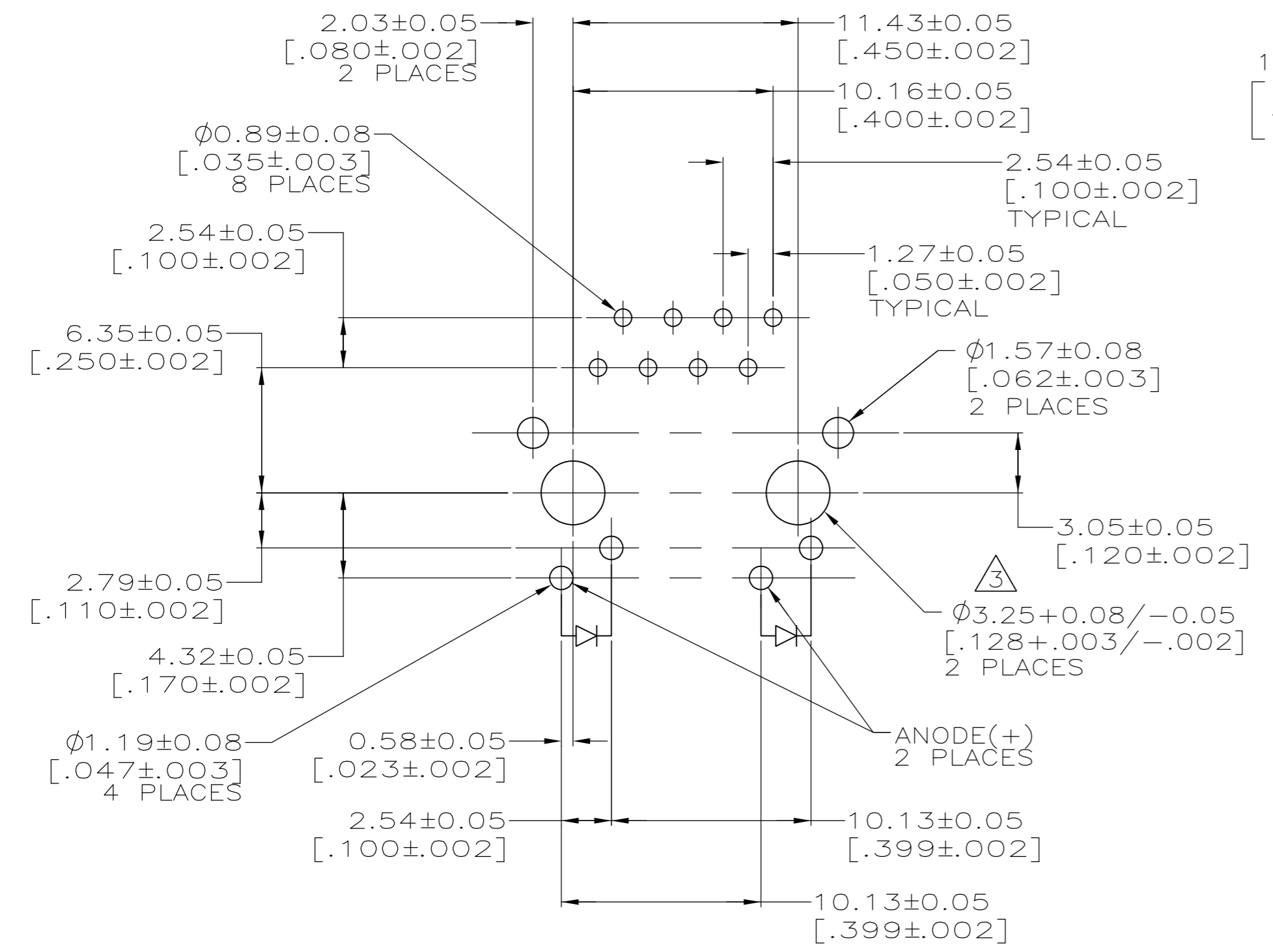
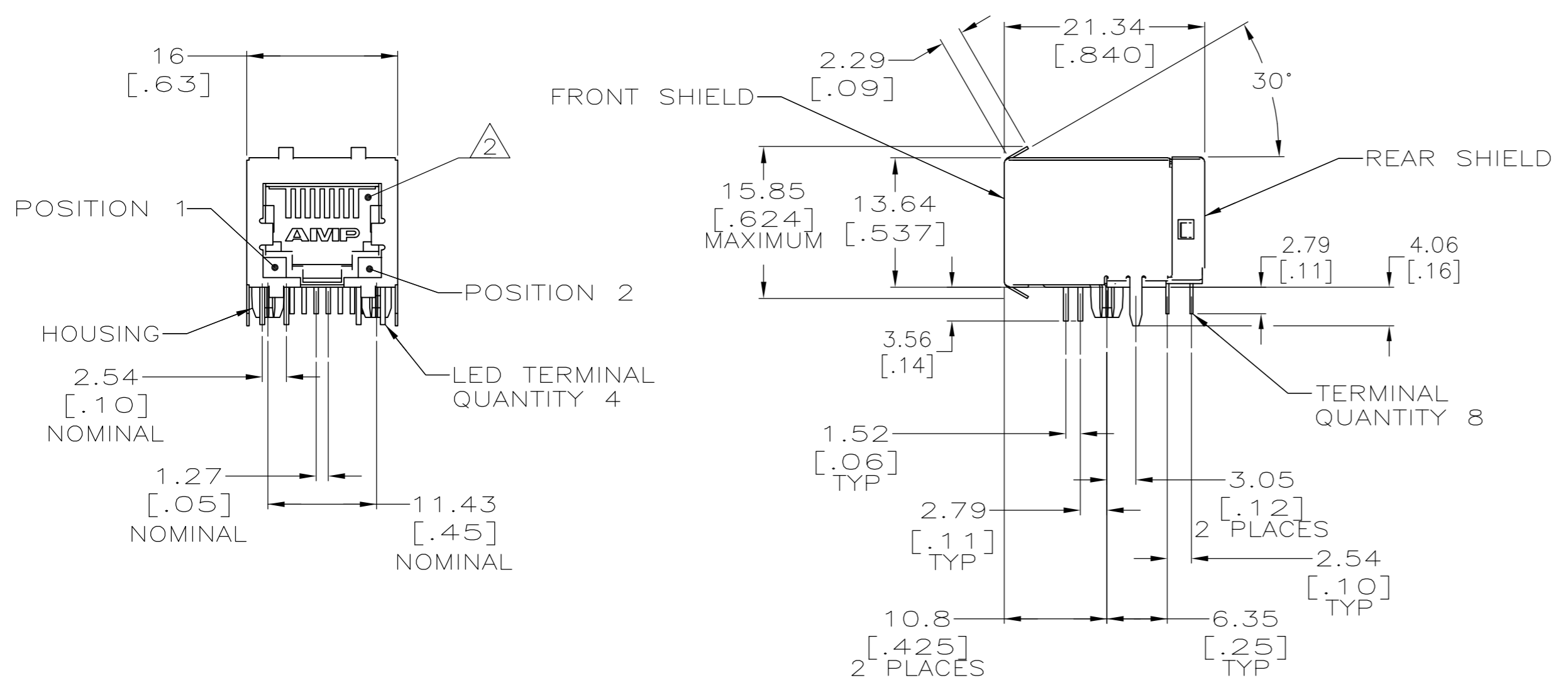
Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China



THIS DRAWING IS UNPUBLISHED. RELEASED FOR PUBLICATION
 © COPYRIGHT - By - ALL RIGHTS RESERVED.

LOC		DIST		REVISIONS			
P	LTR	DESCRIPTION		DATE	DWN	APVD	
AA	00	E2	REVISED PER ECO-11-005033	26MAR11	RK	HMR	



SUGGESTED PC BOARD LAYOUT
 COMPONENT SIDE
 SCALE 4:1

- MATERIAL: HOUSING - PBT THERMOPLASTIC BLACK, UL94V-0.
 TERMINALS - 0.33[.013] THICK PHOS BRONZE PLATED WITH 1.27µm[.000050] MINIMUM THICK HARD GOLD IN LOCALIZED AREA AND 3.81µm[.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27µm[.000050] MINIMUM THICK NICKEL UNDERPLATE.
 SHIELDS - 0.25 [.010] THICK COPPER ALLOY PLATED WITH 1.27µm[.000050] MINIMUM NICKEL AND 2.03 µm[.000080] MINIMUM HOT TIN DIP ON PCB GROUND TABS.
 LIGHT EMITTING DIODE (LED) - DIFFUSED EPOXY LENS, 0.51 x 0.51[.020 x .020] CARBON STEEL WIREFRAME LEADS PREPLATED WITH 8.89 µm[.0003500] THICK Sn/Cu OVER 2.03 µm[.000080] THICK Ag OVER 1.02µm[.000040] THICK Cu OVER 3.56 µm[.000140] THICK Ni OVER 1.02µm[.000040] Cu UNDERPLATE
- JACK CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68 SUBPART F.
- USE #30 DRILL BIT OR 3.25mm DRILL BIT WHEN PRODUCING THESE PCB HOLES.
- THIS MODULAR JACK WITH INTEGRATED LEDS IS NOT IR REFLOW SOLDERING PROCESS COMPATIBLE.

1	YELLOW	GREEN	5569564-5
1	GREEN	GREEN	5569564-4
1	GREEN	YELLOW	5569564-1
MATERIAL	POSITION 1	POSITION 2	PART NUMBER
	LED COLOR		

THIS DRAWING IS A CONTROLLED DOCUMENT.		DWN L. VARELA - DOCK5 07JUN2005	TE Connectivity	
DIMENSIONS: mm [INCHES]		CHK J. WESTMAN 07JUN2005	NAME	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S. FLICKINGER 07JUN2005	MODULAR JACK ASSEMBLY, 8 POSITION, RIGHT ANGLE, LOW PROFILE, PANEL GROUND WITH LEDS	
0 PLC ± -	1 PLC ± -	PRODUCT SPEC 108-1163	SIZE A2	CAGE CODE 00779
2 PLC ± 0.25[.01]	3 PLC ± 0.13[.005]	APPLICATION SPEC 114-2154	DRAWING NO C=5569564	RESTRICTED TO -
4 PLC ± -	ANGLES ± -	WEIGHT -	SCALE 2:1	SHEET 1 of 1
MATERIAL FINISH	CUSTOMER DRAWING		REV E2	